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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Inventors: Jiping Li; Peter G. Borden; Edgar B. Genio  
Title: High Throughput Measurement Of Via Defects In Interconnects  
Serial No.: 10/813,407 Filing Date: March 29, 2004  
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Docket No.: BOX016 US Confirmation No: 5642

Santa Clara, California  
October 2, 2005

Mail Stop AMENDMENT  
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**Second SUPPLEMENTAL INFORMATION DISCLOSURE STATEMENT**

Dear Sir:

Pursuant to 37 C.F.R. § 1.56, §1.97 and §1.98, the Applicants submit for consideration the attached International Search Report and Written Opinion (11 pages total) in a PCT application which claims priority from the current application. Note that these papers were received on Sept 30, and hence no fee should be required. If a fee is required, please charge the deposit account 50-2263 and identify the charge by using the docket number BOX016 US.

The information contained in this Supplemental Information Disclosure Statement is to the best of my knowledge and is not to be construed as a representation that: (i) a complete search has been made; (ii) additional information material to the examination of this application does not exist; (iii) the information, protocols, results and the like reported by third parties are accurate or enabling; or (iv) the above information constitutes prior art to the subject invention.

**CERTIFICATE OF FACSIMILE TRANSMISSION**

I hereby certify that this correspondence is being facsimile transmitted to the U.S. Patent and Trademark Office to the fax number 571-273-8300 on October 2, 2005.

*S. Omkar* *Oct 2, 2005*

Attorney for Applicant(s) Date of Signature

Respectfully submitted,

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Application No. 10/813,407

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